

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Wendy Lee Wilkins et al.

Serial No.: Not Yet Assigned

Art Unit: Not Yet Assigned

Filed: Herewith

Examiner: Not Yet Assigned

For: **INTEGRATED CIRCUIT PACKAGING
APPARATUS AND METHOD**

Attorney Docket No.: 783403605009

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

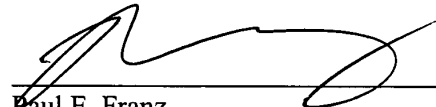
Sir:

This Statement is submitted in compliance with 37 C.F.R. § 1.56.

A list of patent(s) and/or publication(s) not previously submitted is set forth on the attached Form PTO-1449. A copy of each "non patent literature documents" is enclosed.

Any fees required for the proper filing of this Information Disclosure Statement should be withdrawn from the Jones Day Deposit Account No. 50-1432, account 783403605009.

Respectfully submitted,



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Date: December 5, 2003

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Substitute for form 1449/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete if Known	
		Application Number	
		Filing Date	
		First Named Inventor	Wendy Lee Wilkins
		Art Unit	
		Examiner Name	
Sheet	2	of	2
		Attorney Docket Number	783403605009

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		Calmes, S., "Highly Integrated 2-D Capacitive Micromachined Ultrasonic Transducers", IEEE Ultrasonics Symposium, 1999, pgs. 1163-1166	
		Neysmith, Jordan, et al., "High Density Through-Wafer Electrical Interconnects for Direct-Chip-Attach, Device-Scale MEMS Packaging, Micro-Electro-Mechanical Systems (MEMS), vol. 2, 2000, pgs. 595-599	
		Wang, L., et al., "Thinning of Micromachined Wafers for High-Density, Through-Wafer Interconnects," DIMES, Electrical Instrumentation Laboratory, pgs. 121-126.	
		Mullenborn, M., et al., "Chip-size-packaged silicon microphones," Sensors and Actuators A 92, 2001, pgs. 23-29	
		Silicon Microphone for Hearing Instruments, http://www.sonion.com/servlet/page?_dad=portal_EXT&_schema=PORTAL_EXT&_mode... (4 pgs.)	

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

This collection of information is required by 37 CFR 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. **SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.**

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